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Sheet 1 of 3

Form PTO-1449 (modified)
INFORMATION DISCLOSURE CITATION

Atty. Docket No.
9109-33

Serial No.

10/016,578

Applicant:
JAMES D. PARSONS and B. LEO KWAK

Filing Date

11/01/2001

Group

2825

U.S. Patent Documents

| Examiner Initial | Document Number | Date | Name | Class | Subclass |
|------------------|-----------------|---------|-------------------|-------|----------|
| <u>PMR</u> | 4,581,279 | 04/1986 | Sugishita et al. | 428 | 209 |
| <u>PMR</u> | 4,651,192 | 03/1987 | Matsushita et al. | 357 | 74 |
| <u>PMR</u> | 4,775,596 | 10/88 | Holleran et al. | 428 | 432 |
| <u>PMR</u> | 4,810,532-A | 03/1989 | Lavendel et al. | 427 | 255.29 |
| <u>PMR</u> | 5,349,207 | 09/1994 | Malhi | 257 | 76 |
| <u>PMR</u> | 5,877,516 | 03/1999 | Mermagen et al. | 257 | 76 |

Non-Patent Documents

Other Documents (including Author, Title, Source, Date, Pertinent Pages)

PMR Tong, Q.Y.; Gosele, U.; Yuan, C.; Steckl, A. J. and Reiche, M., "Silicon Carbide Wafer Bonding," J. Electrochem. Soc. 142, No. 1, January 1995, pp. 232-236.

PMR Bhattacharya, P. K., "Bonding of SiC slabs for electro-mechanical heat-sinks in advanced packaging applications, Int. J. Electronics Vol. 73, No. 1, pp. 71-82, 1992.

Examiner

Rewro N. Panchajai

Date Considered

9/27/2004

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PNR

Kamijoh, T.; Takano, H. and Sakuta, M., "Heat treatment of semi-insulating InP:FE with phosphosilicate glass encapsulation, Jour. Appl. Phys., Vol. 55, 1984, pp. 3756-3759.

~~Jablonski, J. and Bielawski, W., Electronica, No. 5, 1972, pp. 211-212.~~

PNR

Wong, C.P. and McBride, R., "Robust Titanate-Modified Encapsulants for High Voltage Potting Application of Multichip Module/Hybrid IC," IEEE Transactions on Components, Hybrids and Manufacturing Technology Vol. 16, No. 8, December 1993, pp. 868-875.

PNR

Hunadi, R. and Bilow, N., "Low Expansion Blob Top Encapsulants--A New Generation of Materials for Chip-on-Board and Hybrid Packaging," Proceedings of International SAMPE Symposium and Exhibition: 1st International SAMPE Electronic Conference-Electronic Materials and Processes, Santa Clara, CA, June 23-25, 1987, pp. 397.

PNR

Wong, C. P., "Recent advances in hermetic equivalent flip-chip hybrid IC packaging of microelectronics," Materials Chemistry and Physics 42, 1995, pp. 25-30

PNR

Tudanca, M., Luna, R.G., Fraile, A., Triana, J., Gonzalez, J.M., Vincueria, I. and Dominguez, C., "A Low-Cost Manufacturing Process for High-Density Hybrid Components, Based on Multilayer Polyimide/Ceramic Structures," Proceedings of 42nd Electronic Components and Technology Conference, San Diego, CA, 1992, pp. 120-128.

Examiner

Roxo N. [Signature]

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Savrun, E. and Toy, C., "An Aluminum Nitride Package for 600°C and Beyond," Proc. IEEE, 1998, 0-7803-4540-1/98, pages 265-268,

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Rebecca N. [Signature]

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